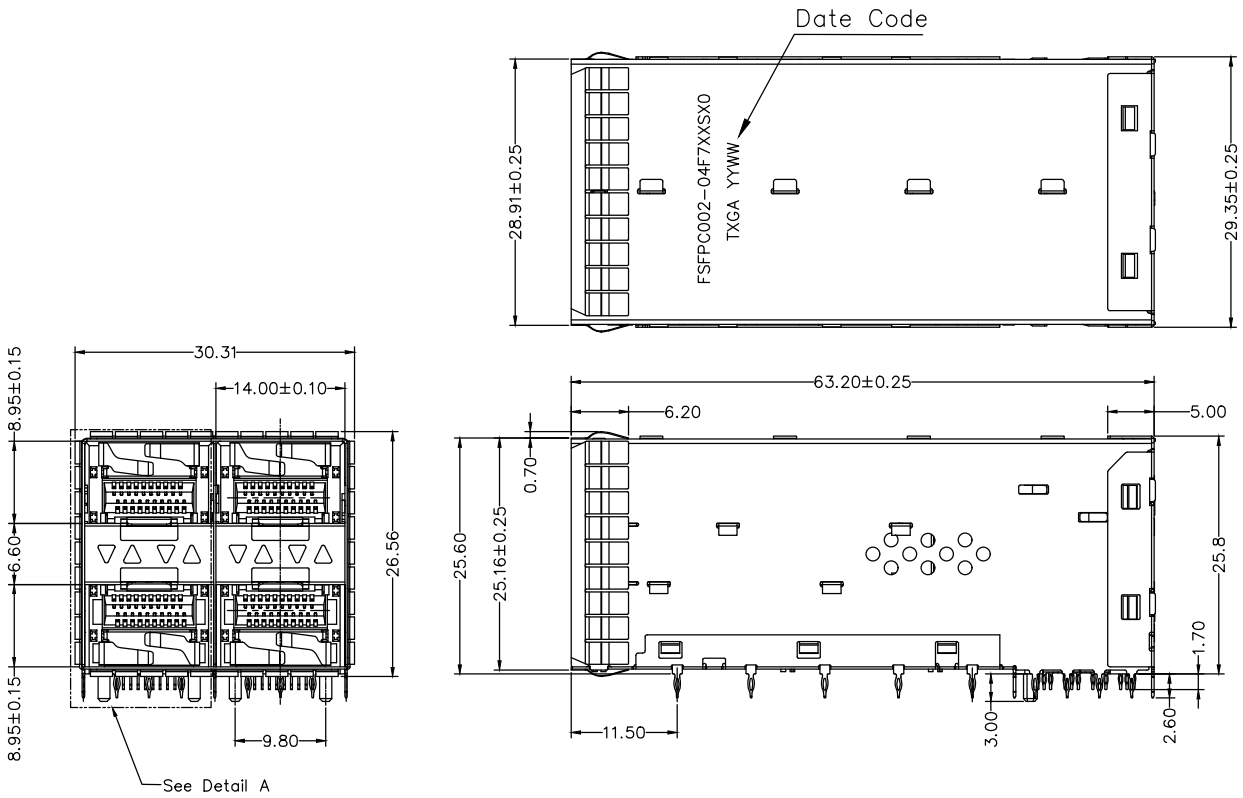
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD



SPECIFICATIONS

Electrical
- Current Rating: 0.5A AC(rms)/DC
- Voltage Rating: 30V AC(rms)/DC
- Contact Resistance: 80 mΩ Max
- Insulation Resistance: 1000 MΩ Min
- Withstanding Voltage: 300V AC r.m.s
- Operating Temperature: −40℃~+85℃
- Storage Temperature: −55℃~+105℃

Material and plating
- Housing: LCP (UL 94V−0) Black
- Moulded Insert: High Temperature Plastic (UL 94V−0) Black
- Light Pipes: PC (UL 94V−0) Clear
- Light Pipe Housing: PBT (UL 94V−0) Black
- Contacts: Copper Alloy/Selective gold plated on contact area and matte tin plated on tails area
- Cage: Copper Alloy/Nickel plating
- EMI Clip: Copper Alloy

Ordering Information

FSFPC	002	—	04	F	7	XX	S	X	0
1	2		3	4	5	6	7	8	

1 Form factor: FSFPC−SFP28

2 Model serial num: 002

3 Port Configuration: 04−4 Ports

4 Mounting Style: F−Through hole press−fit

5 Plating: 7−Selective gold plated on contact area and matte tin plated on tails area

6 Plating Thickness: 15−0.375μm; 30−0.75μm

7 Cage: S−With cage

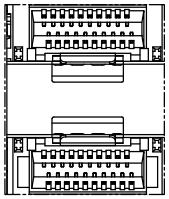
8 Light Pipes:
- 0−Without lightpipe
- 1−With inner and outer lightpipes
- 2−With inner lightpipes
- 3−With outer lightpipes

THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY LEO	DATE 16/Jun/22	PART NO. FSFPC002-04F7XXSX0 / ITEM NO. FSFPC002
DESIGN UNITS METRIC(mm)	X. ±0.30	X.° ±5°	CHECKED BY GISELLE	DATE 16/Jun/22	TITLE Small Form−factor Pluggable 28 90°Angle
	X.X ±0.20	X.X° ±2°			
SCALE 5:1	X.XX ±0.15	X.XX° ±1°	DRAWN BY HJP	DATE 16/Jun/22	REV 0 / SHEET NO. 1/4
SIZE A4	X.XXX ±0.10	X.XXX° ±0.5°			

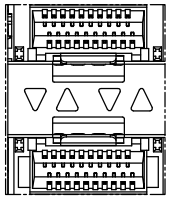
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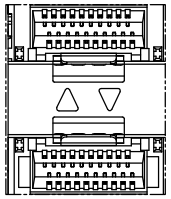
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD



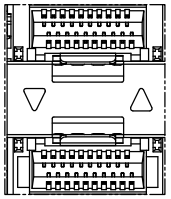
0—Without lightpipe



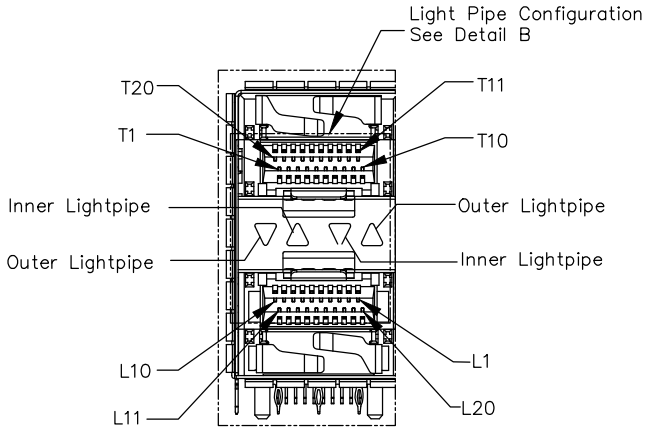
1—With inner and outer lightpipes



2—With inner lightpipes



3—With outer lightpipes



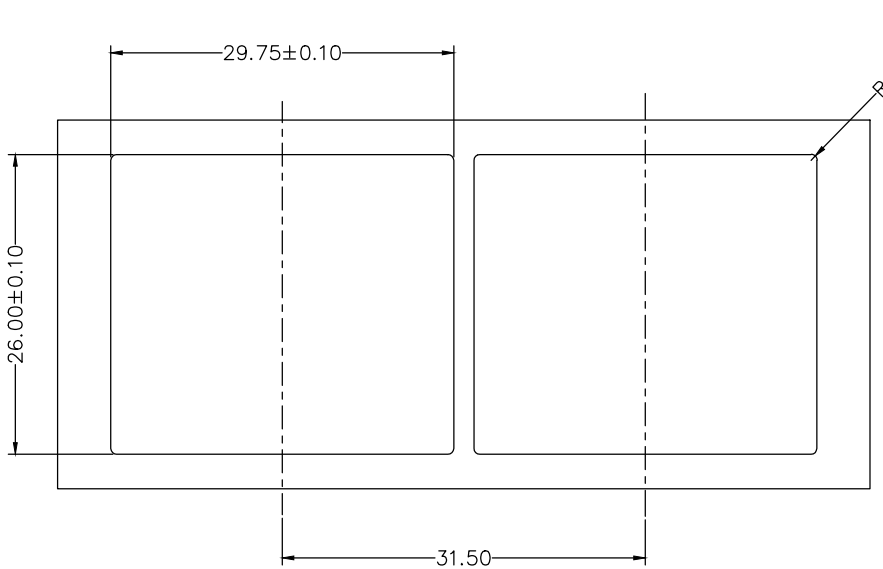
Detail A
Scale2:1

THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY LEO	DATE 16/Jun/22	PART NO. FSFPC002-04F7XXSX0 / ITEM NO. FSFPC002
DESIGN UNITS METRIC(mm)	X. ±0.30	X.° ±5°	CHECKED BY GISELLE	DATE 16/Jun/22	TITLE Small Form-factor Pluggable 28 90°Angle
SCALE 5:1 / SIZE A4	X.X ±0.20	X.X° ±2°	DRAWN BY HJP	DATE 16/Jun/22	REV 0 / SHEET NO. 2/4
	X.XX ±0.15	X.XX° ±1°			
	X.XXX ±0.10	X.XXX° ±0.5°			

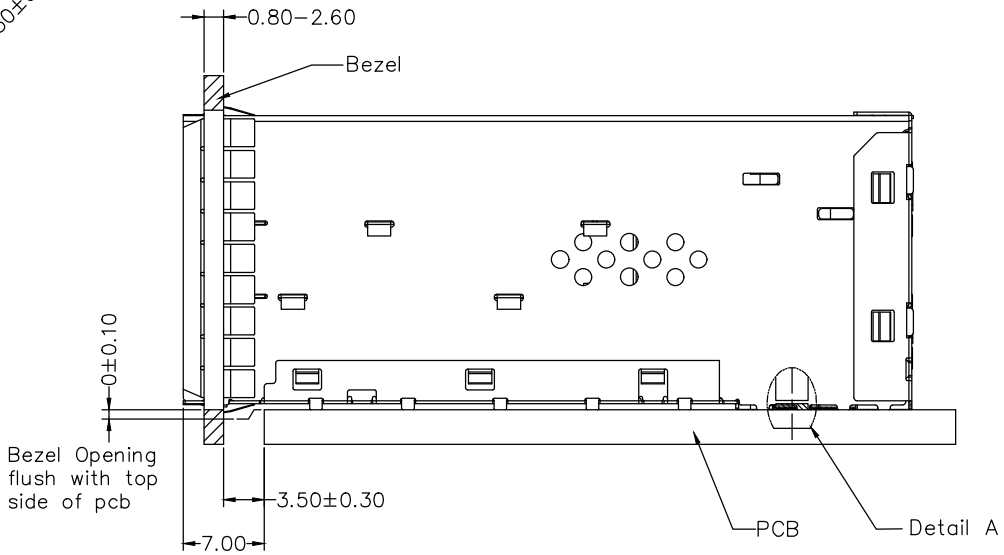
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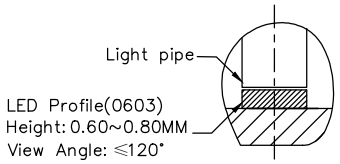
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REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD



Bezel Cut-out Center Spacing Detail
Bezel Thickness: 0.8-2.6



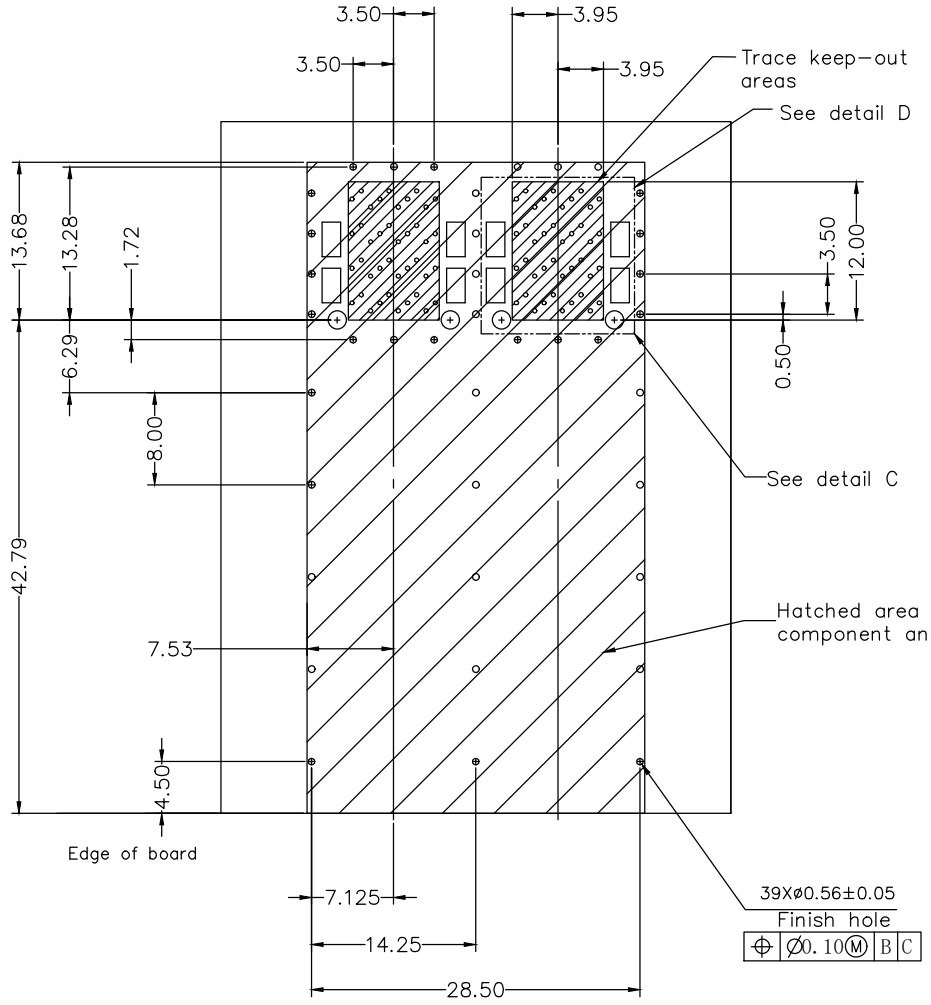


Detail F
Scale 2:1

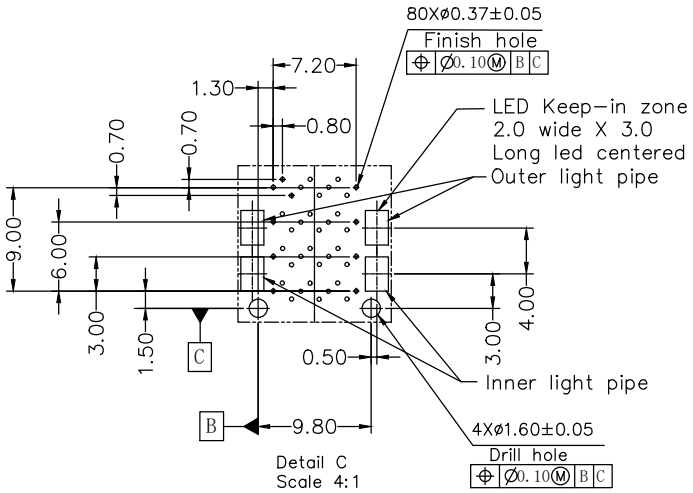
THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY	DATE	PART NO.	ITEM NO.	TXGA Building Technology Cornerstone
			LEO	16/Jun/22	FSFPC002-04F7XXSX0	FSFPC002	
DESIGN UNITS METRIC(mm)	X. ±0.30	X.° ±5°	CHECKED BY	DATE	TITLE		
	X.X ±0.20	X.X° ±2°	GISELLE	16/Jun/22	Small Form-factor Pluggable 28 90°Angle		
SCALE 5:1 / SIZE A4	X.XX ±0.15	X.XX° ±1°	DRAWN BY	DATE		REV 0	SHEET NO. 3/4
	X.XXX ±0.10	X.XXX° ±0.5°	HJP	16/Jun/22			

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REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

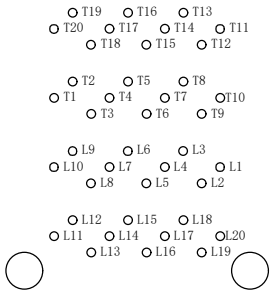


Recommended pcb layout—component side
Recommended pcb thickness—2.63mm



Detail C
Scale 4:1

PIN MAP



Detail D
Scale 8:1

THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY	DATE	PART NO. / ITEM NO.
	X. ±0.30	X.° ±5°	LEO	16/Jun/22	FSFPC002-04F7XXSX0 / FSFPC002
DESIGN UNITS METRIC(mm)	X.X ±0.20	X.X° ±2°	CHECKED BY: GISELLE	DATE: 16/Jun/22	TITLE: Small Form-factor Pluggable 28 90°Angle
SCALE: 5:1 / SIZE: A4	X.XX ±0.15	X.XX° ±1°	DRAWN BY: HJP	DATE: 16/Jun/22	REV 0 / SHEET NO. 4/4
	X.XXX ±0.10	X.XXX° ±0.5°			

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